LNP™ THERMOCOMP™ COMPOUND LF002

LF-1002
REGION EUROPE

DESCRIPTION

LNP THERMOCOMP LF002 compound is based on Polyetheretherketone (PEEK) resin containing 10% glass fiber.

GENERAL INFORMATION	
Features	High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyetheretherketone (PEEK)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Consumer	Commercial Appliance
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL [1]			
Tensile Stress, yield, 5 mm/min	97	MPa	ISO 527
Tensile Strain, yield, 5 mm/min	3.4	%	ISO 527
Tensile Modulus, 1 mm/min	5700	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	162	MPa	ISO 178
Flexural Modulus, 2 mm/min	4700	MPa	ISO 178
IMPACT [1]			
Izod Impact, unnotched 80*10*4 +23°C	49	kJ/m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	6	kJ/m²	ISO 180/1A
THERMAL [1]			
CTE, 23°C to 60°C, flow	3.5E-05	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	5.E-05	1/°C	ISO 11359-2
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	159	°C	ISO 75/Af
PHYSICAL [1]			
Density	1.37	g/cm³	ISO 1183
INJECTION MOLDING [2]			
Drying Temperature	120 – 150	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.1	%	
Melt Temperature	380 – 390	°C	
Front - Zone 3 Temperature	380 – 395	°C	

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Middle - Zone 2 Temperature	365 – 375	°C	
Rear - Zone 1 Temperature	350 – 360	°C	
Mold Temperature	140 – 165	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 – 100	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

DISCLAIMER